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Ding et al.(10) **Pub. No.: US 2023/0232513 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **DRIVER DEVICE LAYOUTS**(52) **U.S. Cl.**(71) Applicant: **TEXAS INSTRUMENTS**
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ABSTRACT(21) Appl. No.: **18/125,931**(22) Filed: **Mar. 24, 2023****Related U.S. Application Data**(63) Continuation of application No. 17/489,228, filed on
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24, 2021.**Publication Classification**(51) **Int. Cl.***H05B 45/30* (2006.01)*H05B 45/40* (2006.01)

An example circuit includes a substrate having a surface and electrically conductive lines. The electrically conductive lines extend in a direction substantially parallel to the surface and substantially orthogonal to a virtual centerline. The circuit also includes first and second instances of a driver device having respective first and second sides, and respective line outputs. The line outputs are arranged along the first side of the respective instance of the driver device, and the respective first side of each of the first and second instances of the driver device are nearer the virtual centerline than the second side thereof. The line outputs of the first instance of the driver device are coupled to a first set of the electrically conductive lines, and the line outputs of the second instance of the driver device are coupled to a second set of the electrically conductive lines.

